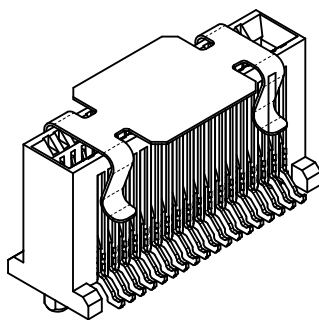
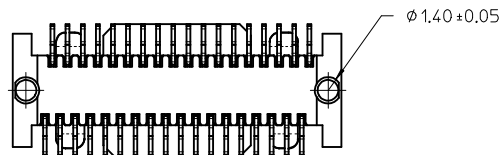
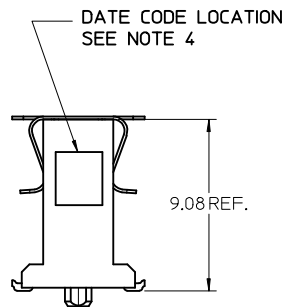
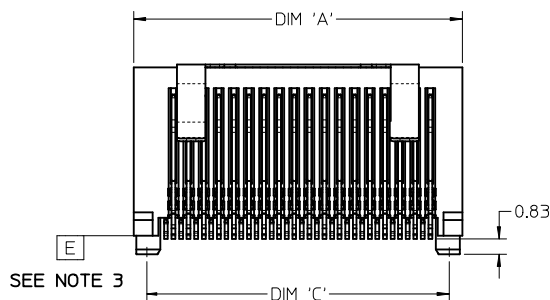
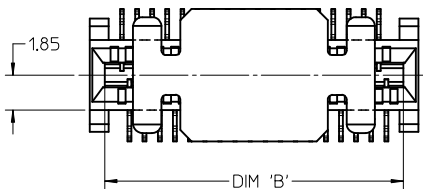




NOTES:

1. MATERIAL:

HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED,
UL 94V-0, BLACK
TERMINALS - COPPER ALLOY

2. TERMINAL PLATING:

OPTION 1

CONTACT AREA: 0.384mm HARD GOLD OVER 2.544mm NICKEL
SOLDER AREA: 2.54-5.094mm TIN OVER 1.274mm NICKEL

OPTION 2

CONTACT AREA: 0.764mm HARD GOLD OVER 2.544mm NICKEL
SOLDER AREA: 2.54-5.094mm TIN OVER 1.274mm NICKEL

3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)

4. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)

5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1

6. MATES WITH INTERNAL CABLE SERIES:

79575/74563/79576/74573/79536/74562/74569/74586

USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002

7. LITTLE ROCK PACKAGING PER PK-75577-001

CHENGDU PACKAGING PER PK-75577-002

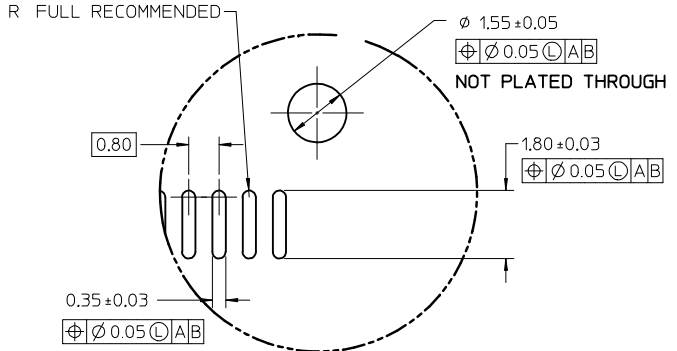
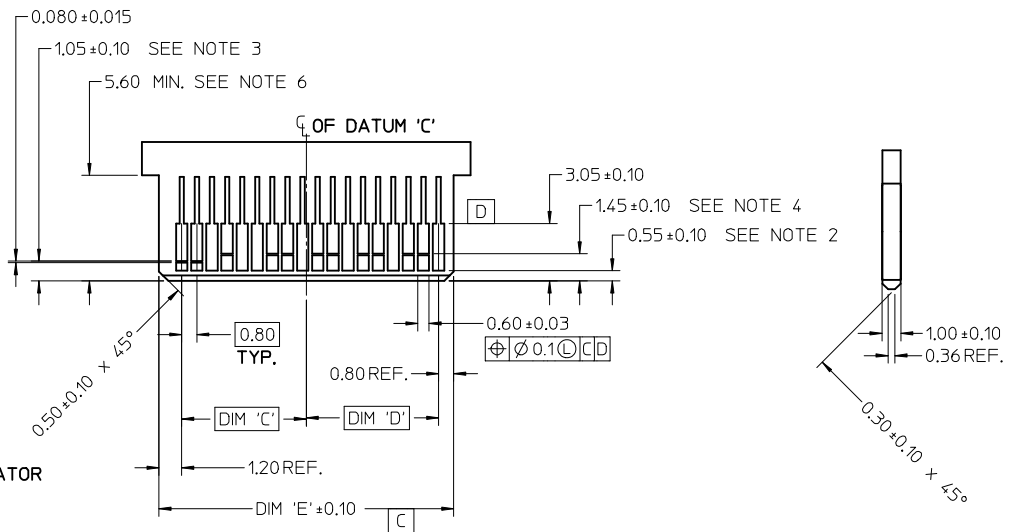
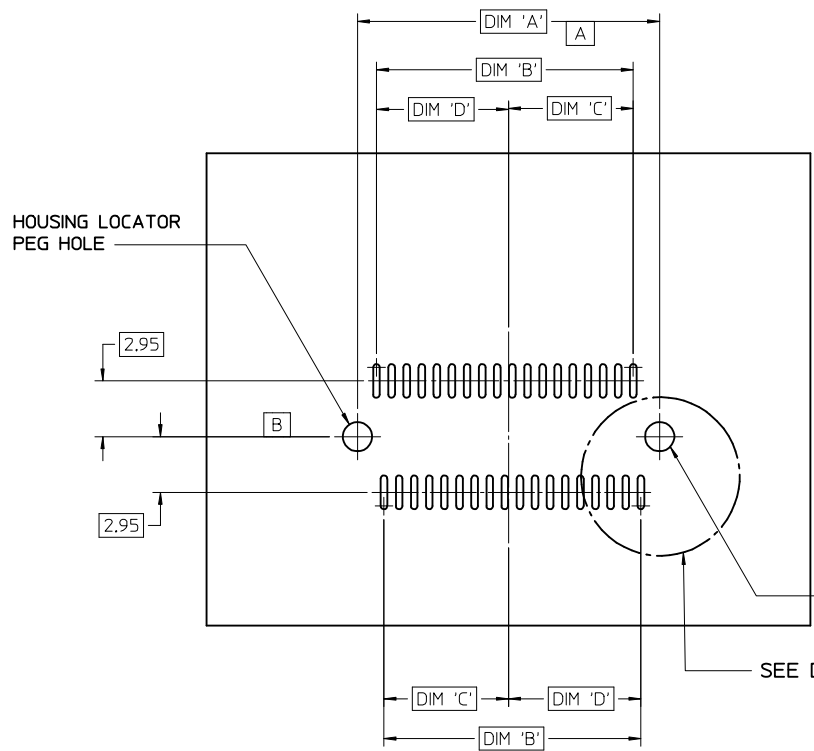
8. CONFORMS TO PRODUCT SPECIFICATION PS-75783-001

9. CONFORMS TO APPLICATION SPECIFICATION AS-75783-001

36 CIRCUIT ASSEMBLY SHOWN

CIRCUIT SIZE	MAT'L NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
26	75577-1001	OPTION 1	13.40	11.80	12.00
26	75577-1005	OPTION 2	13.40	11.80	12.00
36	75577-1002	OPTION 1	17.40	15.80	16.00
36	75577-1006	OPTION 2	17.40	15.80	16.00
50	75577-1003	OPTION 1	23.00	21.40	21.60
50	75577-1007	OPTION 2	23.00	21.40	21.60
68	75577-1004	OPTION 1	30.20	28.60	28.80
68	75577-1008	OPTION 2	30.20	28.60	28.80

REV CHART 50 CKT EC NO: UCP2014-1425 DRAWN BY: DRW:K81NGHAM 2013/09/26 CHKD: TMCLELLAND 2013/09/27 APPR: TMCLELL 2013/09/27	DESCRIPTION	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION ⊙ □			
				mm	INCH	DRAWN BY JLSWENSON	DATE 06/07/07	TITLE SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O				
			4 PLACES	± ---	± ---	CHECKED BY KLANG	DATE 06/07/07					
			3 PLACES	± ---	± ---	APPROVED BY DATE		DOCUMENT NO. SD-75577-002				
			2 PLACES	± 0.13	± ---	MBANAKIS 06/07/07						
			1 PLACE	± 0.25	± ---	MATERIAL NO.						
			0 PLACE	±	±	SEE CHART						
ANGULAR ±1/2°		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS										
REV	SIZE C	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION										



36 CIRCUIT SHOWN
PATTERN FOR REPRESENTATION ONLY

- NOTES:
1. FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
 2. PAD CONFIGURATION FOR FIRST MATE
 3. PAD CONFIGURATION FOR SECOND MATE
 4. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
 5. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
 6. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TOUNGE

	PEG TO PEG	FIRST TO LAST PAD	CENTERLINE TO PAD	CENTERLINE TO PAD	MODULE BOARD WIDTH
CIRCUIT SIZE	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

SEE SHEET 1 EC NO: UCP2014-1425 DRAWN BY: DRINKBINGHAM 2013/09/26 CHKD: MCCELLEND 2013/09/27 APPR: MCCELLEND 2013/09/27	QUALITY SYMBOLS ▽=0 ▽=0 ▽=0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			mm		INCH		TITLE		SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O molex		
			4 PLACES	± ---	± ---	DRAWN BY JLSWENSON	DATE 06/07/07	DOCUMENT NO. SD-75577-002			
			3 PLACES	± ---	± ---	CHECKED BY KLANG	DATE 06/07/07			SHEET NO. 2 OF 2	
			2 PLACES	± 0.13	± ---	APPROVED BY MBANAKIS	DATE 06/07/07				
ANGULAR ±1/2°			MATERIAL NO.		SEE SHEET 1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SIZE C								